

Notice of References Cited	Application/Control No. 10/026,176	Applicant(s)/Patent Under Reexamination SEO ET AL.	
	Examiner Brian L. Mutschler	Art Unit 1753	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,011,580	04-1991	Pan et al.	205/118
	B	US-6,146,517	11-2000	Hoinkis, Mark D.	205/186
	C	US-6,162,365	12-2000	Bhatt et al.	216/13
	D	US-			
	E	US-			
	F	US-			
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	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
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	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Copper Interconnect Films," http://www.appliedmaterials.com/products/copper_interconnect_films.html (no date).
	V	"Polyimide," http://www.plasticsusa.com/tpi.html (no date).
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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